

## Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

[Vishay/Siliconix](#)  
[IRFD9010](#)

For any questions, you can email us directly:

[sales@integrated-circuit.com](mailto:sales@integrated-circuit.com)



# IRFD9010, SiHFD9010

Vishay Siliconix

## Power MOSFET

PRODUCT SUMMARY		
$V_{DS}$ (V)	- 50	
$R_{DS(on)}$ ( $\Omega$ )	$V_{GS} = -10$ V	0.50
$Q_g$ (Max.) (nC)	11	
$Q_{gs}$ (nC)	3.8	
$Q_{gd}$ (nC)	4.1	
Configuration	Single	

### FEATURES

- For Automatic Insertion
- Compact, End Stackable
- Fast Switching
- Low Drive Current
- Easy Paralleled
- Excellent Temperature Stability
- P-Channel Versatility
- Compliant to RoHS Directive 2002/95/EC

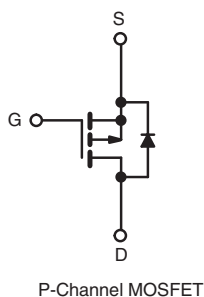
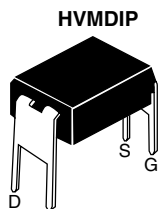

 Available  
**RoHS\***  
 COMPLIANT

### DESCRIPTION

The HVMDIP technology is the key to Vishay's advanced line of power MOSFET transistors. The efficient geometry and unique processing of the HVMDIP design achieves very low on-state resistance combined with high transconductance and extreme device ruggedness.

The p-channel HVMDIPs are designed for application which require the convenience of reverse polarity operation. They retain all of the features of the more common n-channel HVMDIPs such as voltage control, very fast switching, ease of paralleling, and excellent temperature stability.

P-channels HVMDIPs are intended for use in power stages where complementary symmetry with n-channel devices offers circuit simplification. They are also very useful in drive stages because of the circuit versatility offered by the reverse polarity connection. Applications include motor control, audio amplifiers, switched mode converters, control circuits and pulse amplifiers.



ORDERING INFORMATION	
Package	HVMDIP
Lead (Pb)-free	IRFD9010PbF
	SiHFD9010-E3
SnPb	IRFD9010
	SiHFD9010

ABSOLUTE MAXIMUM RATINGS ( $T_C = 25^\circ\text{C}$ , unless otherwise noted)				
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-Source Voltage		$V_{DS}$	- 50	V
Gate-Source Voltage		$V_{GS}$	$\pm 20$	
Continuous Drain Current	$V_{GS}$ at - 10 V	$I_D$	$T_C = 25^\circ\text{C}$	- 1.1
			$T_C = 100^\circ\text{C}$	- 0.68
Pulsed Drain Current <sup>a</sup>		$I_{DM}$	- 8.8	A
Linear Derating Factor			0.01	
Inductive Current, Clamped	$L = 100 \mu\text{H}$ see fig. 14	$I_{LM}$	- 8.8	A
Inductive Current, Unclamped (Avalanche Current)	see fig. 15	$I_L$	- 1.5	
Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	$P_D$	1	W
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to + 150	$^\circ\text{C}$
Soldering Recommendations (Peak Temperature)	for 10 s		300 <sup>d</sup>	

#### Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = -25$  V, starting  $T_J = 25^\circ\text{C}$ ,  $L = 52$  mH,  $R_g = 25 \Omega$ ,  $I_{AS} = -2.0$  A (see fig. 12).
- $I_{SD} \leq -4.0$  A,  $di/dt \leq 75$  A/ $\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 175^\circ\text{C}$ .
- 1.6 mm from case.

\* Pb containing terminations are not RoHS compliant, exemptions may apply

# IRFD9010, SiHFD9010

Vishay Siliconix



THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient	$R_{thJA}$	-	120	°C/W

SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$		- 50	-	-	V
$V_{DS}$ Temperature Coefficient	$\Delta V_{DS}/T_J$	Reference to $25\text{ }^\circ\text{C}$ , $I_D = -1\text{ mA}$		-	- 0.091	-	V/°C
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$		- 2.0	-	- 4.0	V
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20\text{ V}$		-	-	$\pm 500$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -50\text{ V}, V_{GS} = 0\text{ V}$		-	-	- 250	$\mu\text{A}$
		$V_{DS} = -40\text{ V}, V_{GS} = 0\text{ V}, T_J = 125\text{ }^\circ\text{C}$		-	-	- 1000	
On-State Drain Current	$I_{D(on)}$	$V_{GS} = 10\text{ V}$	$V_{DS} > I_{D(on)} \times R_{DS(on)}$ max.	- 1.1	-	-	A
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = -10\text{ V}$	$I_D = -0.58\text{ A}^b$	-	0.35	0.50	$\Omega$
Forward Transconductance	$g_{fs}$	$V_{DS} = -20\text{ V}, I_D = -2.4\text{ A}$		1.7	2.5	-	S
<b>Dynamic</b>							
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{ V},$ $V_{DS} = -25\text{ V},$ $f = 1.0\text{ MHz}$ , see fig. 5		-	240	-	pF
Output Capacitance	$C_{oss}$			-	160	-	
Reverse Transfer Capacitance	$C_{rss}$			-	30	-	
Total Gate Charge	$Q_g$	$V_{GS} = -10\text{ V}$	$I_D = -4.7\text{ A}, V_{DS} = 0.8\text{ V}$ see fig. 6 and 13 <sup>b</sup>	-	7.2	11	nC
Gate-Source Charge	$Q_{gs}$			-	2.5	3.8	
Gate-Drain Charge	$Q_{gd}$			-	2.7	4.1	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -25\text{ V}, I_D = -4.7\text{ A}$ $R_g = 24\text{ }\Omega, R_D = 5.6\text{ }\Omega,$ see fig. 10 <sup>b</sup>		-	6.1	9.2	ns
Rise Time	$t_r$			-	47	71	
Turn-Off Delay Time	$t_{d(off)}$			-	13	20	
Fall Time	$t_f$			-	39	59	
Internal Drain Inductance	$L_D$	Between lead, 6 mm (0.25") from package and center of die contact		-	4.0	-	nH
Internal Source Inductance	$L_S$			-	6.0	-	
<b>Drain-Source Body Diode Characteristics</b>							
Continuous Source-Drain Diode Current	$I_S$	MOSFET symbol showing the integral reverse p - n junction diode		-	-	- 1.1	A
Pulsed Diode Forward Current <sup>a</sup>	$I_{SM}$			-	-	- 8.8	
Body Diode Voltage	$V_{SD}$	$T_J = 25\text{ }^\circ\text{C}, I_S = -0.7\text{ A}, V_{GS} = 0\text{ V}^b$		-	-	- 5.5	V
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25\text{ }^\circ\text{C}, I_F = -4.7\text{ A}, dI/dt = 100\text{ A}/\mu\text{s}^b$		33	75	160	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$			0.090	0.22	0.52	$\mu\text{C}$
Forward Turn-On Time	$t_{on}$	Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )					

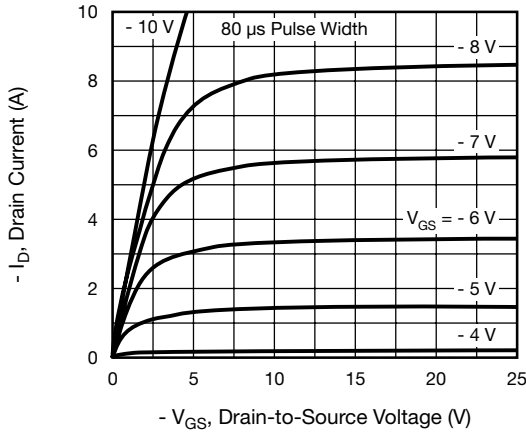
**Notes**

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .

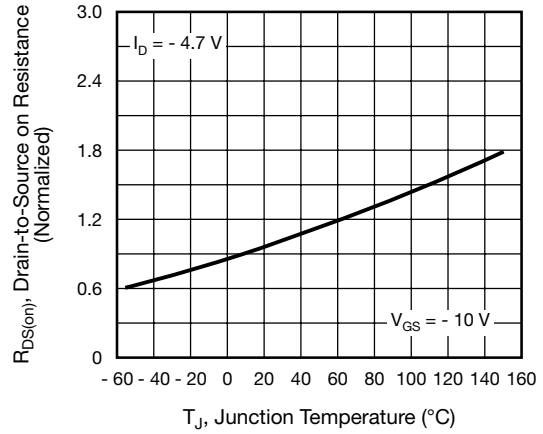


**IRFD9010, SiHFD9010**  
 Vishay Siliconix

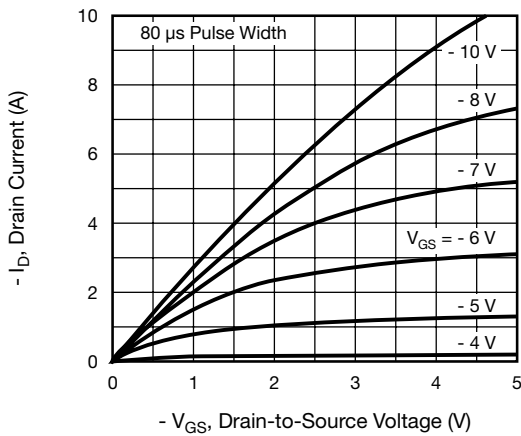
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



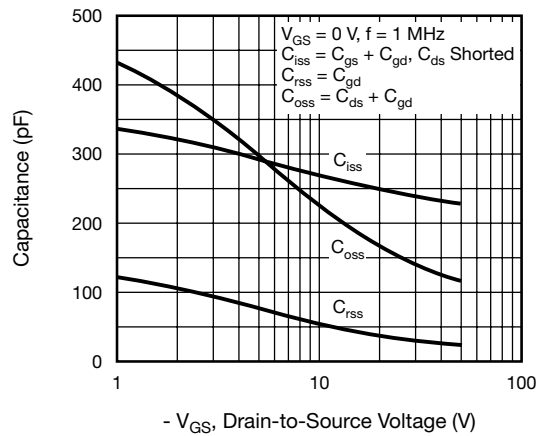
**Fig. 1 - Typical Output Characteristics**



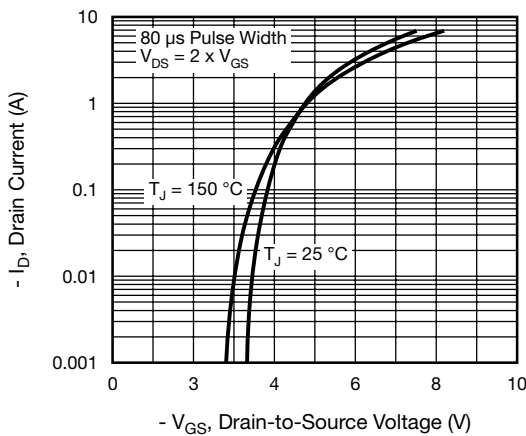
**Fig. 4 - Normalized On-Resistance vs. Temperature**



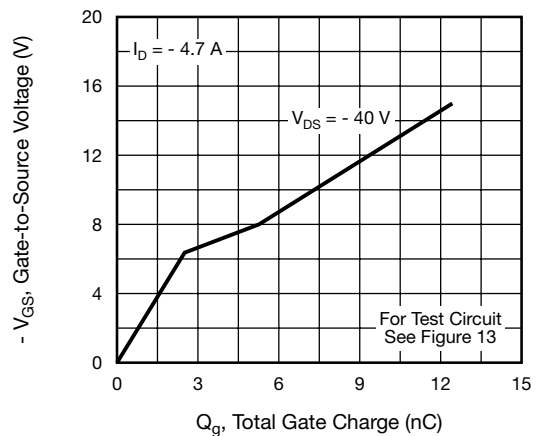
**Fig. 2 - Typical Output Characteristics**



**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**



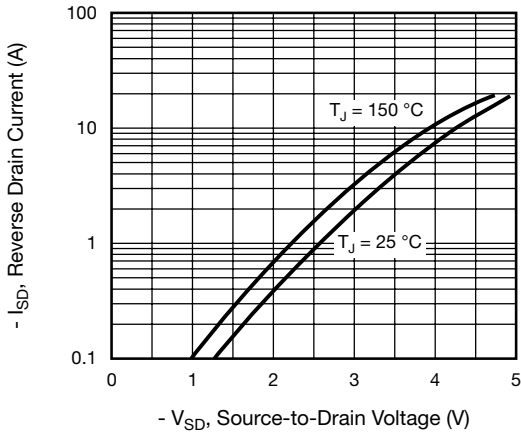
**Fig. 3 - Typical Transfer Characteristics**



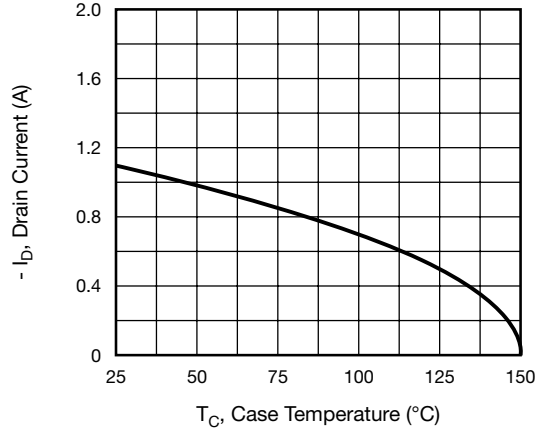
**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**

# IRFD9010, SiHFD9010

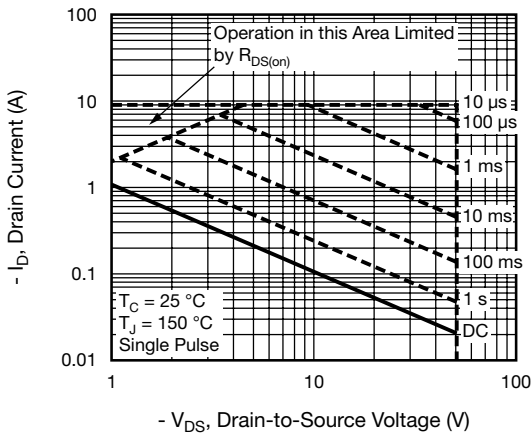
Vishay Siliconix



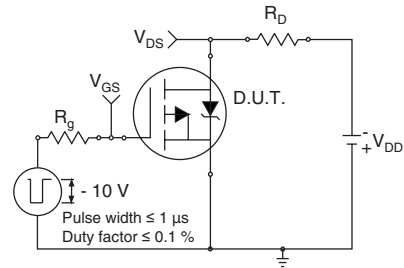
**Fig. 7 - Typical Source-Drain Diode Forward Voltage**



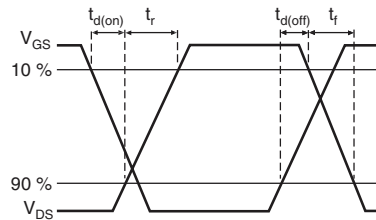
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



**Fig. 8 - Maximum Safe Operating Area**



**Fig. 10a - Switching Time Test Circuit**

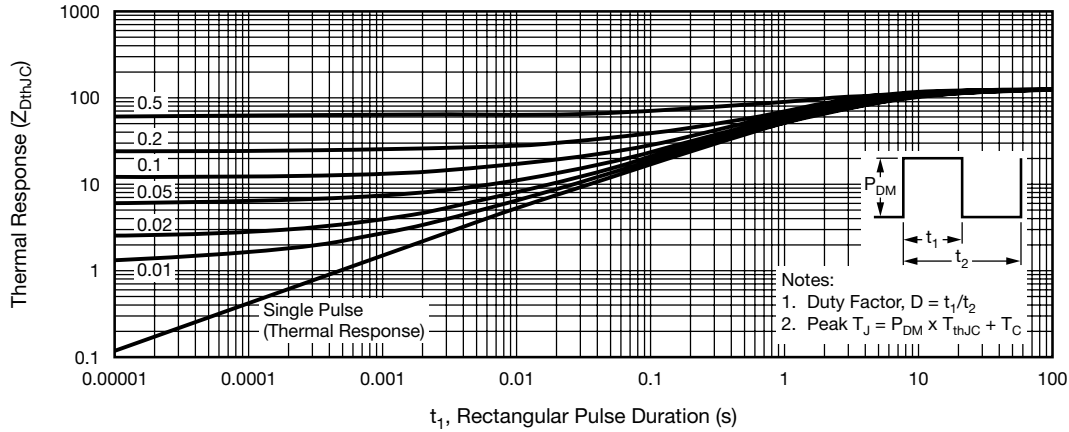


**Fig. 10b - Switching Time Waveforms**

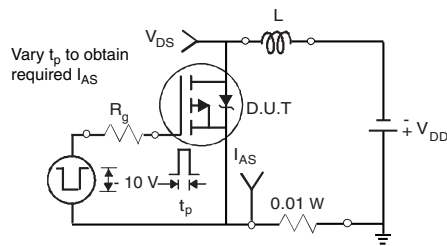


**IRFD9010, SiHFD9010**

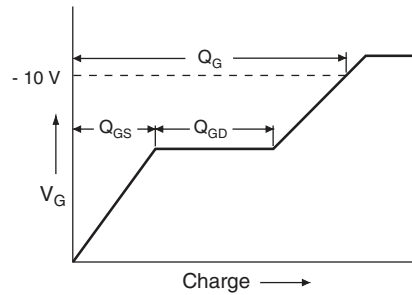
Vishay Siliconix



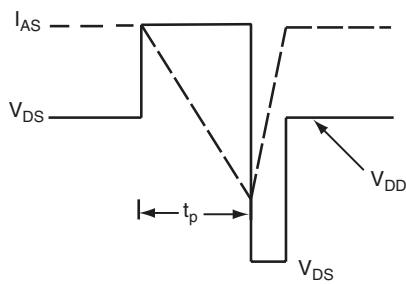
**Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case**



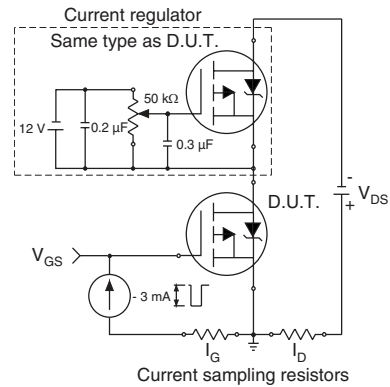
**Fig. 12a - Unclamped Inductive Test Circuit**



**Fig. 13a - Basic Gate Charge Waveform**



**Fig. 12b - Unclamped Inductive Waveforms**



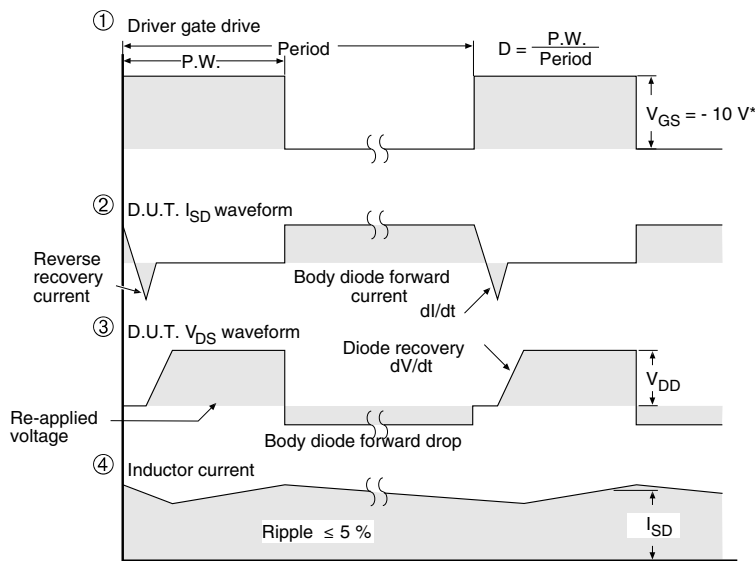
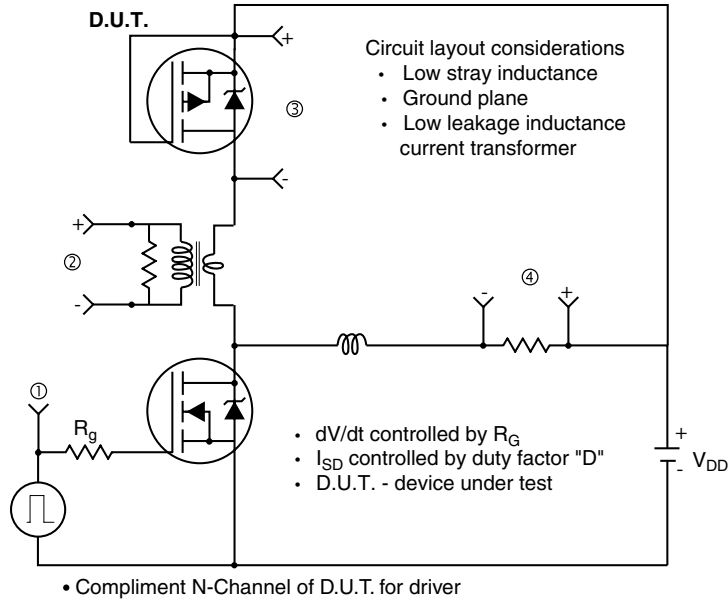
**Fig. 13b - Gate Charge Test Circuit**

# IRFD9010, SiHFD9010

Vishay Siliconix



## Peak Diode Recovery dV/dt Test Circuit



\*  $V_{GS} = -5V$  for logic level and  $-3V$  drive devices

Fig. 14 - For P-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see [www.vishay.com/ppg291405](http://www.vishay.com/ppg291405).



### Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.